

AMENDMENTS TO THE SPECIFICATION

Page 5, please amend the paragraph commencing at line 17 by rewriting same to read as follows:

The present invention has another object to provide a printer in which a printed wiring board on which electronic parts are to be mounted is brought while being held in generally upright position to make it possible to print solder to the land on either side of the printed wiring board at a the same time, and which thus enables a more compact design of the electronics packaging system and higher speed of cream solder printing.

Page 6, please amend the paragraph commencing at line 2 by rewriting same to read as follows:

The present invention has a still another object to provide a novel electronics packaging system in which a printed wiring board on which electronic parts are to be mounted is brought while being held in a generally upright position to make it possible to print solder to the land on either side of the printed wiring board at a the same time, and place and solder the electronic parts on the lands, and which thus enables a more compact design of the electronics packaging system and improved efficiency of electronics packaging.

Page 6, please amend the paragraph commencing at line 9 by rewriting same to read as follows:

The present invention has a yet another object to provide a reflow unit in which a printed wiring board on which electronic parts are to be mounted is brought while being held in a generally upright position to solder the electronic parts to either side of the printed wiring board at a the same time, and which thus enables a more compact design of the electronics packaging system and higher speed of soldering.

Page 6, please amend the paragraph commencing at line 14 by rewriting same to read as follows:

The present invention has a yet still another object to provide an electronic part placing unit in which a printed wiring board on which electronic parts are to be mounted is brought while being held in a generally upright position to place electronic parts on either side of the printed wiring board at a the same time, and which thus enables a more compact design of the electronics packaging system and higher speed of electronic part placing.

Page 7, please amend the paragraph commencing at line 7 by rewriting same to read as follows:

The printed wiring board is brought by a transfer mechanism, while being held in a generally upright position, through the printer, placing unit and reflow unit in this order. That is, the printer, placing unit and reflow unit are provided to face either side of the printed wiring board brought while being held in a generally upright position to

print solder to either side of the printed wiring board at the same time, then place electronic parts on either side of the printed wiring board at the same time, and melt and cool the printed solder to solder the electronic parts placed on either side of the printed wiring board.

Page 13, please amend the paragraph commencing at line 2 by rewriting same to read as follows:

First the printer 3 to print cream solder to either land of a printed wiring board is a screen printer, and includes, as shown in FIGS. 2 and 3, a transfer mechanism 11 to ~~bright~~ bring a printed wiring board 2 while keeping it in a generally upright position, a screen mechanism 12 to print cream solder to either land of the printed wiring board ~~2supported 2~~ supported by the transfer mechanism 11, a squeegee mechanism 13 to squeeze cream solder supplied to the screen mechanism 12 to the printed wiring board 2, and a drive mechanism 14 to slide the squeegee mechanism 13 towards the screen mechanism 12.

Page 40, please amend the paragraph commencing at line 7 by rewriting same to read as follows:

As shown in FIG. 23, the guide mechanism 144 to guide the up-down movement of the part holding mechanism 142 in the second position includes first and second guide members 162 and 163. The first guide member 162 is disposed above the second guide member 163, and has a guide slot 164. The guide slot 164 consists of a first straight portion 164a to engage

the gear 158 with the rack 159 of the above-mentioned turning mechanism 143, an inclined portion 164b formed contiguously to the first straight portion 164a and obliquely in the transfer mechanisms 121a to 121d of the first guide member 162, and a second straight portion 164c formed contiguously to the inclined portion 164b and in parallel to the first straight portion 164a on the side of the transfer mechanisms 121a to 121d. The second guide member 163 has a driving mechanism 166 to move the electronic part 10 towards the printed wiring board 2 for placement on the latter. The driving mechanism 166 is a cylinder mechanism to move the second guide member 163 in the up-down moving direction of the part holding mechanism 142, that is, in a direction generally perpendicular to the direction of arrow J and opposite direction in FIG. 23, and includes a shaft 167 and cylinder 168 fixed to the second guide member 163. When the part holding mechanism 142 has moved the guide slot 165, the second guide member 163 move in the direction of arrow K J in FIG. 23 towards the printed wiring board 2 in relation to the first guide member 162. The second guide member 163 is thus moved by the driving mechanism 166 in the direction of arrow K J in FIG. 23, and the suction head 146 places the electronic part 10 held thereby on the printed wiring board 2. The shaft 151 of the part holding mechanism 142 is engaged in the guide slots 164 and 165.